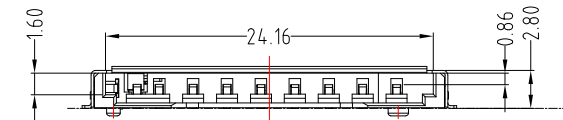


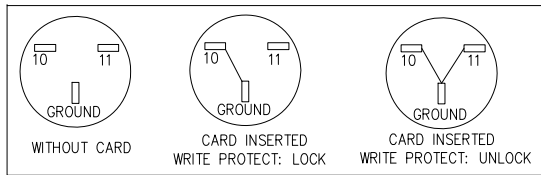
PAD AREA  
 KEEP OUT AREA

RECOMMENDED P.C.B LAYOUT



SD CARD PIN DESIGN

PIN NO.	NAME	DESCRIPTION
1#	CD/DAT3	CARD DETECT/DATA I/O
2#	CMD	COMMAND
3#	VSS1	GROUND
4#	VDD	POWER
5#	CLK	CLOCK
6#	VSS2	GROUND
7#	DAT0	DATA I/O
8#	DAT1	DATA I/O
9#	DAT2	DATA I/O
10#	CD	Card Detect pin
11#	WP	Write Protect pin



- 1.MATERIAL:
- 1.1 HOUSING: LCP
  - 1.2 CONTACT: PHOSPHOR BRONZE
  - 1.3 COVER: BRASS
- 2.PLATING:
- 2.1 CONTACT: PLATED GOLD IN MATING AREA ;  
TIN PLATED ON SOLDER BALLS ;  
NICKEL UNDER PLATED OVERALL
  - 2.2 SHELL: NICKEL UNDER PLATED SURFACE LAYER

- 3.ELECTRICAL & MECHANICAL PARAMETER
- 3.1 RATING: 250V , 0.5A
  - 3.2 CONTACT RESISTANCE: 100mΩ MAX
  - 3.3 INSULATION RESISTANCE: 1000MΩ MIN
  - 3.4 WITHSTANDING STRENGTH: 500V AC
  - 3.5 INSERTION FORCE: 10N MAX
  - 3.6 SEPARATION FORCE: 2N MIN
  - 3.7 OPERATING TEMPERATURE: -25°C ~ 90°C

**CONTACT** 建倚科技股份有限公司  
CONTACT TECHNOLOGY CORP.

TOLERANCE UNLESS OTHERWISE STATED :

Up to 5	±0.2
Above 5 ~ 15	±0.3
Above 15 ~ 30	±0.4
Above 30 ~ 50	±0.5
Angle	±0.3°

3RD. ANGEL'S

DRAWN BY:	DATE	MAT'L	TITLE	CONNECTOR
Jack Lu	06/09/23		MODLE	SD 短體卡座 H3.09mm
CHECKED BY:	DATE	FINISH	DWG NO.	SD-TF125001-HF-S267
Jacky Chen	06/09/23		SCALE	1 : 1
APPROVED BY:	DATE	SHEET NO.	PART NO.	SD-TF125001-HF-S267
Tony Kao	06/09/23	1 of 3		

ITEM NO.	DESCRIPTION	DRAWN	DATE
1	更新料號	Jack	060923